Product / Package Information

Package	TQFP_EP
Body Size (mm)	14 X 14 X 1.0 (6.5 EP)
Lead Count	100
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A and B

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica fused	60676-86-0	2.89E-01	88	880000	56.74	567390
Thermosets	Epoxy & Phenol resin	Proprietary	3.77E-02	11.5	115000	7.41	74148
Other inorganic materials	Carbon black	1333-86-4	1.64E-03	0.5	5000	0.32	3224
Subtotal			3.28 E-01	100.00	1000000	64.48	644761

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.39E-01	99.25	992500	27.30	273013
Copper & its alloys	Chromium	7440-47-3	4.20E-04	0.30	3000	0.08	825
Copper & its alloys	Tin	7440-31-5	3.50E-04	0.25	2500	0.07	688
Copper & its alloys	Zinc	7440-66-6	2.80E-04	0.20	2000	0.06	550
Subtotal			1.40 E-01	100.00	1000000	27.51	275076

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	5.60 E-04	100.0	1000000	0.11	1101

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.98 E-03	100.0	1000000	1.77	17664

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	2.10 E-03	100.00	1000000	0.41	4132

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.42 E-02	100.0	1000000	4.77	47668

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	3.53E-03	72.40	724000	0.69	6950
Thermoset	Epoxy compound	Proprietary	8.83E-04	18.10	181000	0.17	1737
Other organic materials	Anhydrides	Proprietary	3.31E-04	6.79	67900	0.07	652
Other organic materials	Polymeric material	Proprietary	1.32E-04	2.71	27100	0.03	260
Subtotal	Subtotal		4.88 E-03	100.00	1000000	0.96	9599

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.09 E-01**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

Product / Package Information

Package	TQFP_EP
Body Size (mm)	14 X 14 X 1.0 (6.5 EP)
Lead Count	100
Terminal Finish	SnPb

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
JIG Material Content Compliant	No

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica fused	60676-86-0	2.89E-01	88	880000	56.74	567390
Thermosets	Epoxy & Phenol resin	Proprietary	3.77E-02	11.5	115000	7.41	74148
Other inorganic materials	Carbon black	1333-86-4	1.64E-03	0.5	5000	0.32	3224
Subtotal			3.28 E-01	100.00	1000000	64.48	644761

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.39E-01	99.25	992500	27.30	273013
Copper & its alloys	Chromium	7440-47-3	4.20E-04	0.30	3000	0.08	825
Copper & its alloys	Tin	7440-31-5	3.50E-04	0.25	2500	0.07	688
Copper & its alloys	Zinc	7440-66-6	2.80E-04	0.20	2000	0.06	550
Subtotal			1.40 E-01	100.00	1000000	27.51	275076

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	5.60 E-04	100.0	1000000	0.11	1101

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.63 E-03	85.0	850000	1.50	15014
Tin & its alloys	Lead	7439-92-1	1.35 E-03	15.0	150000	0.26	2650
Subtotal			8.98 E-03	100.0	1000000	1.77	17664

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	2.10 E-03	100.00	1000000	0.41	4132

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.42 E-02	100.0	1000000	4.77	47668

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
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Other organic materials	Polymeric material	Proprietary	1.32E-04	2.71	27100	0.03	260
Subtotal	Subtotal		4.88 E-03	100.00	1000000	0.96	9599

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.09 E-01**	100.00	1000000

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